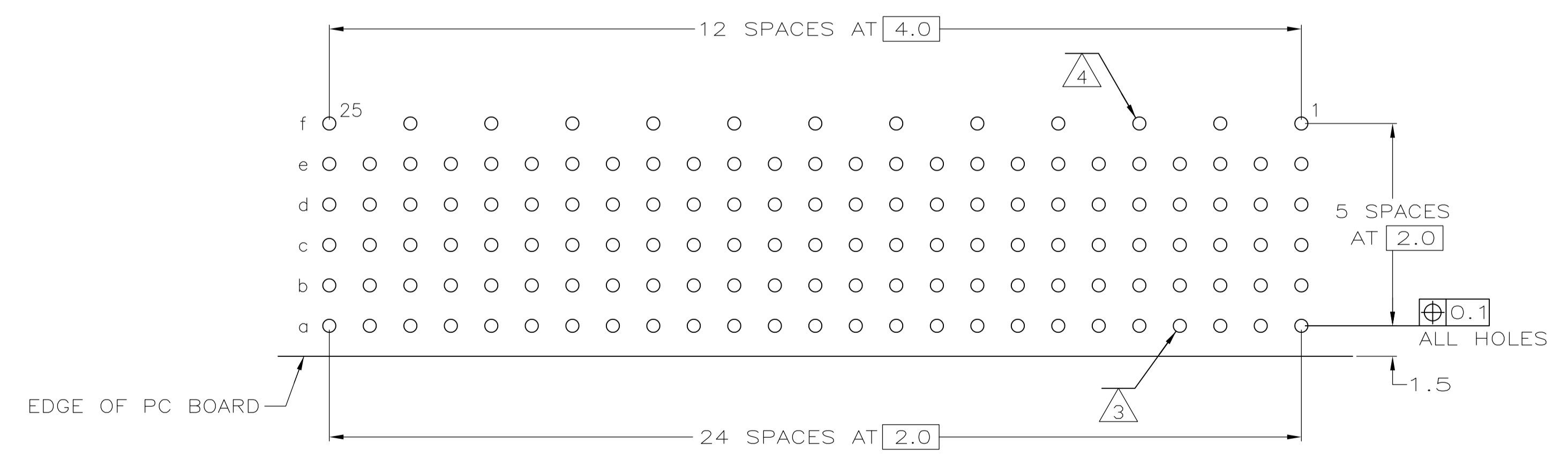
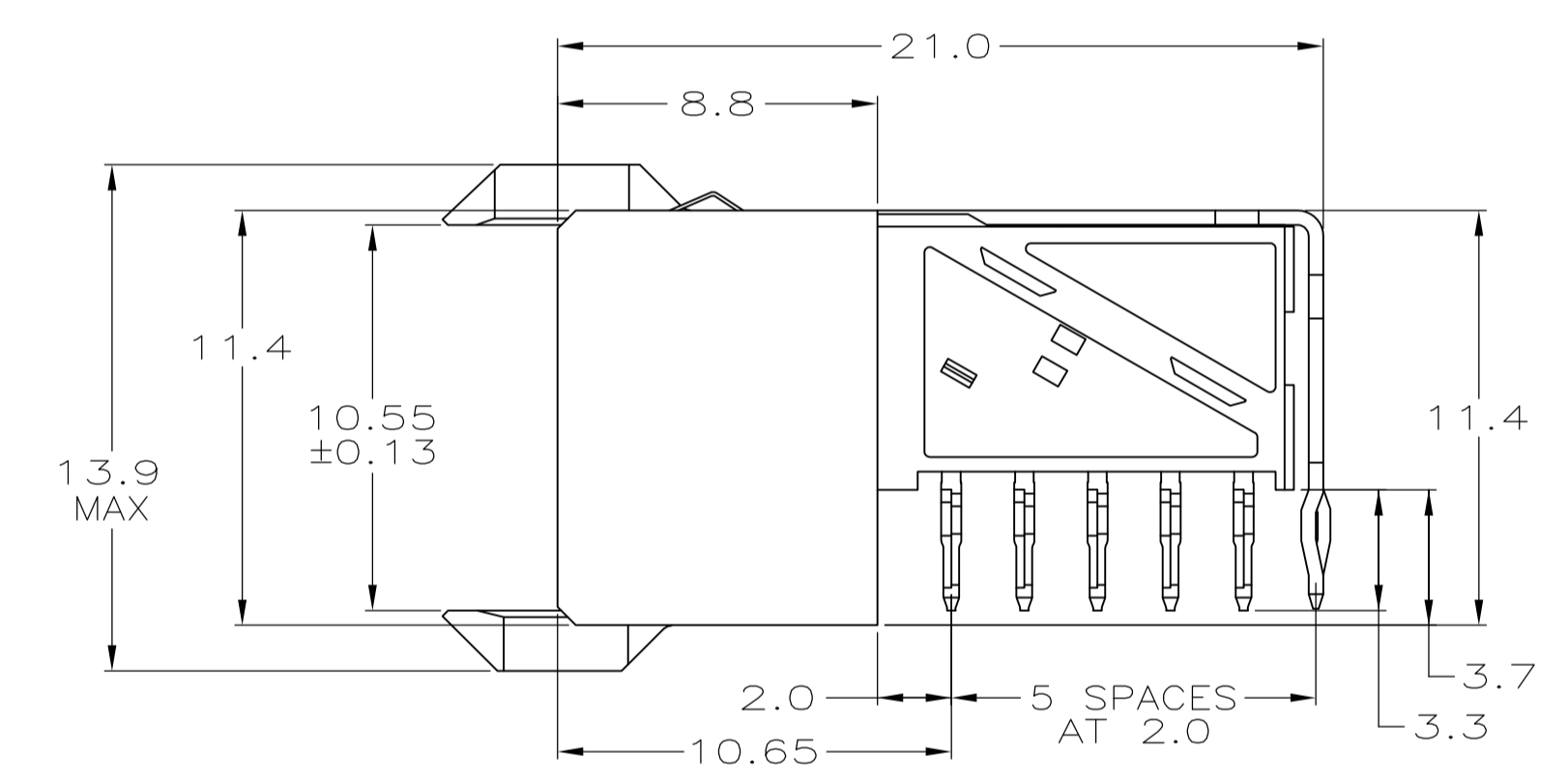
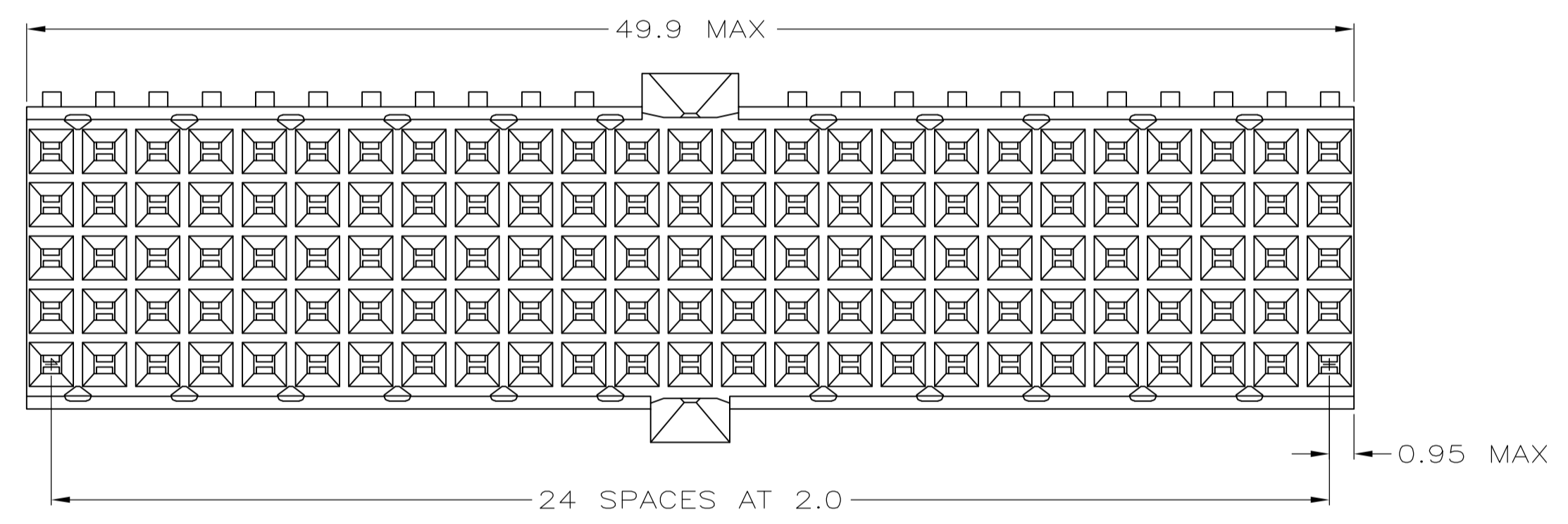


- 1 MATERIAL:
CONTACT: PHOSPHOR BRONZE.
HOUSING: GLASS-FILLED POLYESTER.
- 2 GENERAL PLATING SPECIFICATION: UNDERPLATING (ENTIRE CONTACT): 1.27µm MIN NICKEL AND ACTION PIN: 0.5µm MIN TIN LEAD. FOR PLATING OF MATING SURFACES SEE APPLICABLE SPECIFICATION REFERENCE FOR EACH DASH NUMBER.
- 3 PLATED THROUGH HOLES AT 2mm x 2mm GRID.
- 4 ROW "f" 13 PLATED THROUGH HOLES FOR UPPER SHIELD.
- 5 SHIELD MOUNTED ON CONNECTOR WITH DOUBLE SIDED ADHESIVE TAPE OR ADHESIVE.
- 6 CONNECTOR MARKED WITH PART NUMBER AND DATE CODE.
- 7 1.27µm GOLD PLATING ON MATING SURFACES.
- 8 CONFORMS TO ALL TESTING ACCORDING TO IEC 61076-4-101 PERFORMANCE LEVEL 1.



COMPONENT SIDE AS SHOWN
 RECOMMENDED PCB HOLE LAYOUT

PCB HOLE DIMENSIONS FOR ACTION PIN
 DRILLED HOLE: 0.700±0.025mm
 FINISHED HOLE: 0.55 TO 0.65mm
 CU-THICKNESS: 0.025 TO 0.050mm
 SN/PB-THICKNESS: 0.004 TO 0.010mm

FINISH	1645579-1
PART NUMBER	

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN D. HUMBERT 10/25/2010	Tyco Electronics Corporation Harrisburg, PA 17105-3608
DIMENSIONS: mm		CIK D. YI 10/25/2010	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD D. YI 10/25/2010	NAME
0 PLC	± -	PRODUCT SPEC	RECEPTACLE ASSEMBLY, Z-PACK
1 PLC	± -	APPLICATION SPEC	2mm HM, TYPE A/B
2 PLC	± 0.1	SIZE	A1
3 PLC	± -	WEIGHT	00779
4 PLC	± -	CUSTOMER DRAWING	1645579
ANGLES	± -	SCALE	5:1
MATERIAL	SEE TABLE	SHEET	1 OF 1
		REV	A